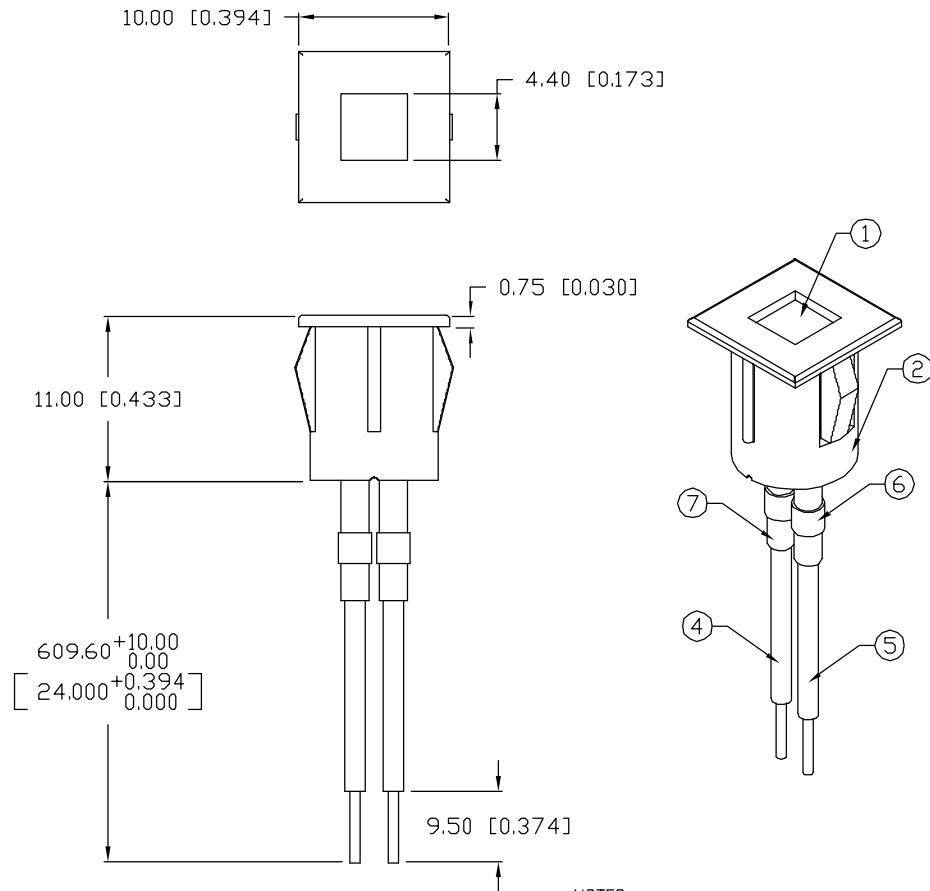


UNCONTROLLED DOCUMENT

PART NUMBER  
SSI-LXH55YD-600

REV.



ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585		nm	
FORWARD VOLTAGE		2.1	2.8	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_f=100\mu\text{A}$
AXIAL INTENSITY		10		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		110		2x theta	
EMITTED COLOR:	YELLOW				
EPOXY LENS FINISH:	YELLOW DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

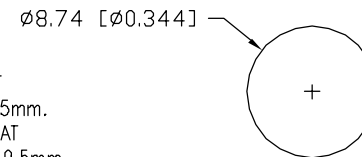
PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	35	mA
STEADY CURRENT	20	mA
POWER DISSIPATION	110	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING, STORAGE TEMP.	-40 TO +85	°C
SOLDERING TEMP.	+260	°C
2.0 mm FROM BODY		5 SEC. MAX

\*  $t < 10\mu\text{s}$

NOTES:

- SSH-LXH55, BLACK NYLON HOLDER.
- SSL-LX5573YD, YELLOW LED.
- PANEL CUT OUT: 8.45mm [0.345] SQR.
- ANODE LEAD: LXP-WST24RDT0C, 24 AWG. TINNED OVERCOAT WIRE, RED INSULATION, CUT 595mm LONG, STRIP 3mm & 9.5mm.
- CATHODE LEAD: LXP-WST24BLT0C, 24 AWG. TINNED OVERCOAT WIRE, BLACK INSULATION, CUT 595mm LONG, STRIP 3mm & 9.5mm.
- CRIMP WIRE LEADS TO LED LEADS.
- 32mm 1/16" BLACK HEAT SHRINK TUBING. (2 PCS.)

PANEL CUTOUT:



\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN=+DECIMAL PRECISION MAX.=+0.00 -DECIMAL PRECISION

REV.

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5mm x 5mm 585nm YELLOW LED, PANEL INDICATOR,  
YELLOW DIFFUSED LENS, 24" WIRE LEADS.

RELIABILITY NOTE  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: JN	CHECKED BY:	APPROVED BY:	DATE: 02.19.09
			PAGE: 1 OF 1
			SCALE: N/A